

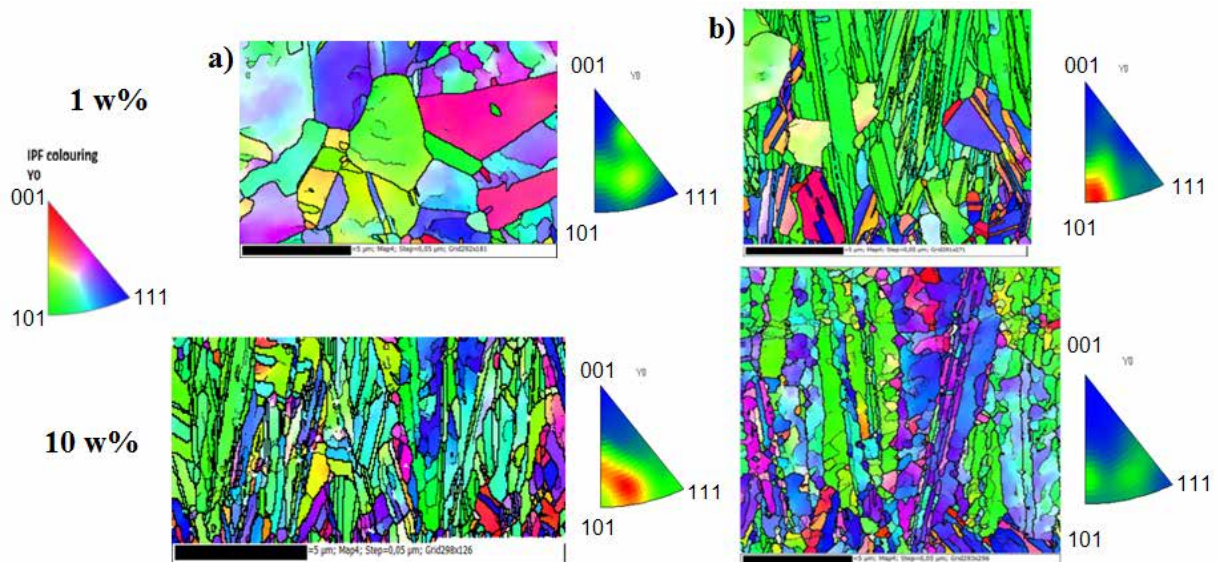
# Microstructure of Cu deposits fabricated from water-containing deep eutectic solvents

*P. Valverde*<sup>a</sup>, A. Mulone<sup>b</sup>, U. Klement<sup>b</sup>, T. Green<sup>a</sup> and S. Roy<sup>a</sup>

<sup>a</sup> Strathclyde University, James Weir building, 75 Montrose Street, 4<sup>th</sup> Floor, Scotland-United Kingdom, *priscila.valverde-armas@strath.ac.uk, todd.green@strath.ac.uk and sudipta.roy@strath.ac.uk*

<sup>b</sup> Chalmers University of Technology, SE-412 96 Goteborg, Sweden, *mulone@chalmers.se and uta.klement@chalmers.se*

Deep eutectic solvents (DESS) are a promising type of Ionic Liquids (ILs) for metal electrodeposition due to their properties. Although DESS are hygroscopic substances, most of the studies have been performed from dry DES systems. This work aims to elucidate the effect of water on metal electrodeposition from water-containing DESS.



**Figure 1.** EBSD maps and IPF of Cu deposits at the a) centre and b) edge fabricated from electrolytes containing 1 and 10 wt% of H<sub>2</sub>O.

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